



DISCRIPTION

FEATURES

Multilayer ceramic structure Closed magnetic circuit Avoids crosstalk Excellent solderability High reliability

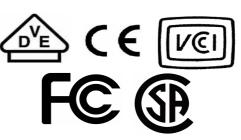
OPTIONS

Tape & Reel is Standard (Qty: 2.000 Pcs) Bulk Packing Available for smaller quantites Tolerance: K=10%, M=20% is Standard, tighter Tolerance available (MOQ on request)

APPLICATIONS

VCRs Mobile Radios Cordless Telephones Modems Global Position Systems Wirless Communications Equipment Network Systems Computer Products

APPROVAL



PHYSICAL CHARACTERISTICS

- Testing : (Equivalents acceptable) Inductance & Q-HP4195A + HP41951 DCR : VOAC-7412 ; SRF : HP8753C
- Solderability : 90% of the terminal Electrode shall be covered Preheat : 260°C ± 5°C for 160 second Solder : H63AA Eutectic Solder ; Flux : Rusin, DIP for 5 seconds ± 1 second
- Thermal Shock : Inductance shall be within ± 5% of initial value when temperature is -40°C and 85°C for 30 min. for each 100 cycles
- Operating Temperature : -25°C ~ 85°C
- Storage Temperature : -40°C ~ 85°C

Properties	Test conditions		Value	Unit	Tol.		
Inductance		L	33	μH	see Site 2		
Q factor		Q	30		min.		
DC-resistance		DCR typ.		Ω	typ.		
DC-resistance		DCR max.	1,40	Ω	max.		
Self-Res. Freq.		SRF	16	Mhz	min.		
Test-Freq.			1	Mhz			
Rated Current		IDC	5	mA	max.		
Saturation Current		Isat		mA	typ.		

ELECTRICAL SPECIFICATIONS

1. This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical,					SMT Multi-Layer Ceramic Chip Inductors		
public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon –Components must be informed before the stage of design-in. Evaluation checks for safety have to be					Part No.:	S11006-330	
performed on each electronic components used in electrical circuits that require high safety and reliability functions.					Customer:		
DRW:	Chang	CHKD	Young	MATL:	Chu Chi	DATE	08.06.2009
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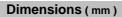
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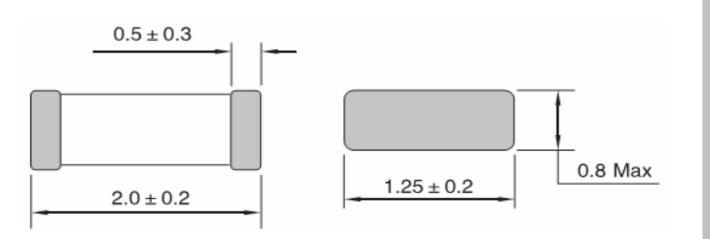
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TECHNICAL INFORMATIONS



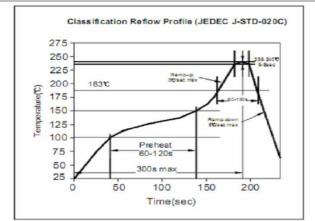


Ordering Information

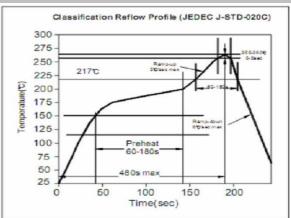
Serie and Range S11006-330

Tolerance	ROHS	Packing		
K	R	TR		
K = 10%	R = ROHS	BU = Bulk Ware		
M = 20%	N = non ROHS	TR = Tape Reel		
N = 30%				

Soldering Profile for Lead Free Soldering 235-240°C



Soldering Profile for Lead Free Soldering 255-260°C



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